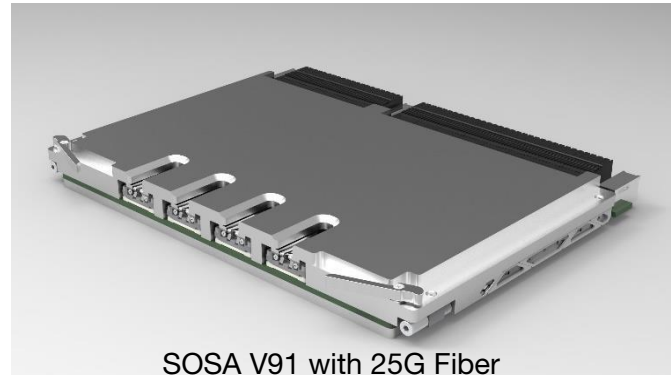


6U VPX SOSA ALIGNED VITA 91 ETHERNET SWITCH

Ruggedized High Density Ethernet switch with 25G or 50G Fiber

PDS - 372



DESCRIPTION

The 6U VPX V91 SOSA-aligned high-speed, high-density 25G/50 G Ethernet switches, builds on our trusted 10Gbps technology available in both 3U and 6U configurations. The 6U V91 switches are offered in two versatile configurations: 240 channels: Backplane – 192 channels at 50G; Front Panel – 48 channels at 25G; 216 channels: Backplane – 192 channels at 50G; Front Panel – 24 channels at 50G. Designed with flexibility in mind, these switches are fully configurable to meet diverse system requirements. They provide adaptability in system connectivity, speeds, port types, and seamless interoperability with various media converters and connectors. This unmatched versatility stems from cutting-edge product design and engineering innovation. To optimize usability, the switches feature advanced management software that includes a command-line interface (CLI), SNMP support, and web-based configuration tools. The software is equipped with a comprehensive suite of capabilities, including virtualization, quality of service (QoS), security, tunneling, Precision Time Protocol (PTP), and more.

FEATURES & BENEFITS

- Version 1: 240 channels: CF-02W600-10X
 - Backplane: 184 channels at 50G
 - Front Panel: 48 channels at 25G
- Version 2: 216 channels: CF-02W600-11X
 - Backplane: 184 channels at 50G
 - Front Panel: 24 channels at 50G
- Total switching throughput of 10.4 Tbps
- Line rate forward of X & Y
- L2 / L3 managed switch
- PTP IEEE 1588v1/v2 support; other specialized functions
- Available in conduction and air-cooled configurations for -40-85C environments as well as harsh vibration profiles

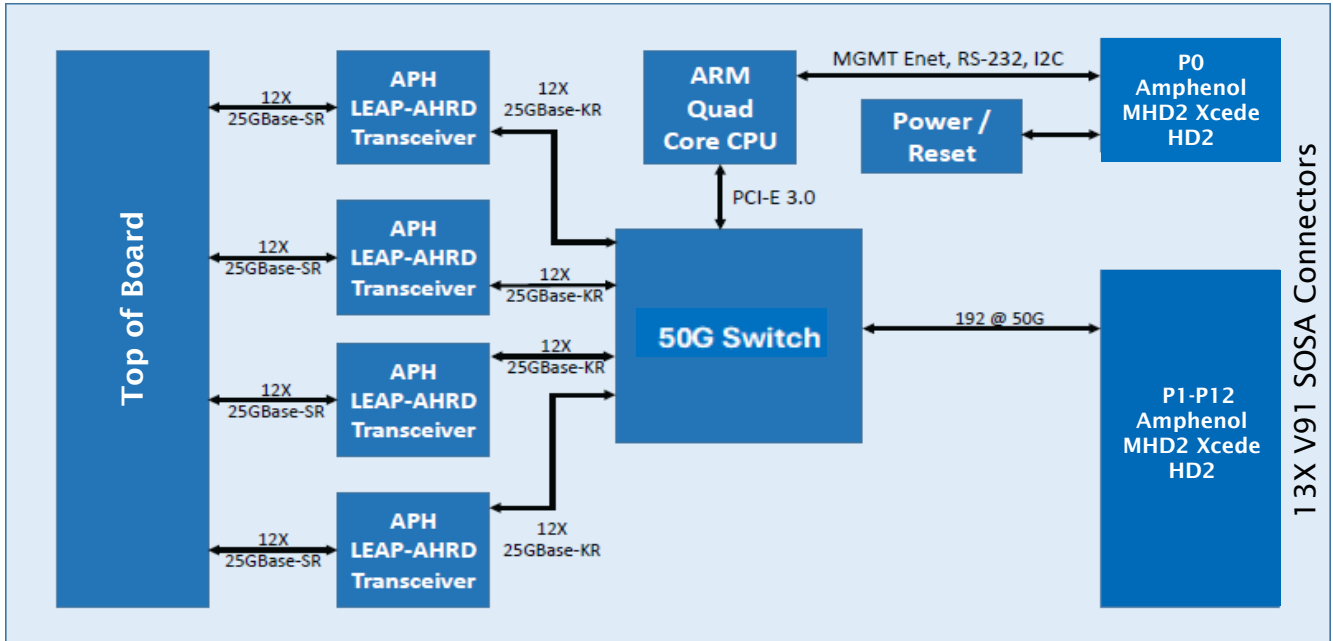
ORDERING INFORMATION

Part Number	Channels	Backplane	Front Panel
CF-02W600-10X	232	184@50G	48@25G
CF-02W600-11X	208	184@50G	24@50G

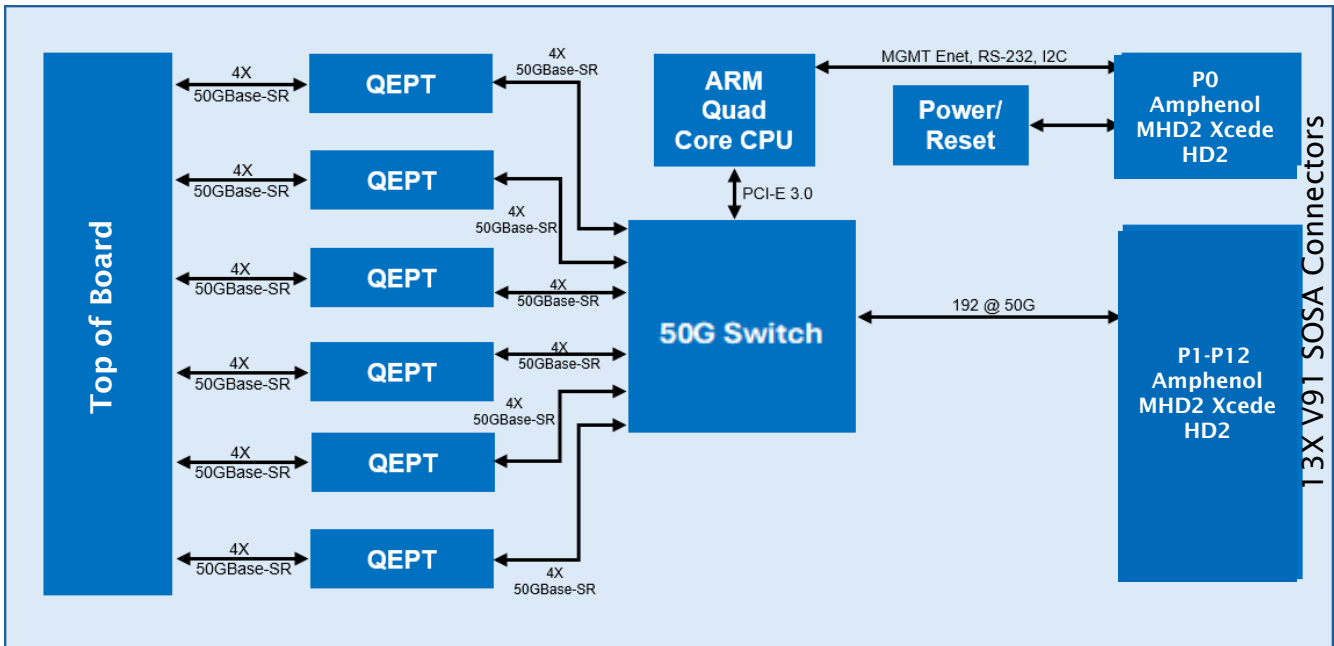
For other options, please contact the factory.

BLOCK DIAGRAMS

CF-02W600-10X



CF-02W600-11X



ETHERNET INTERFACES

- 1X 100/1GBase-T Management Interface + RS232 Serial Console
- Version 1: 232 channels: CF-02W600-10X
 - Backplane: 184 channels at 50G
 - Front Panel: 48 channels at 25G
- Version 2: 208 channels: CF-02W600-11X
 - Backplane: 184 channels at 50G
 - Front Panel: 24 channels at 50G

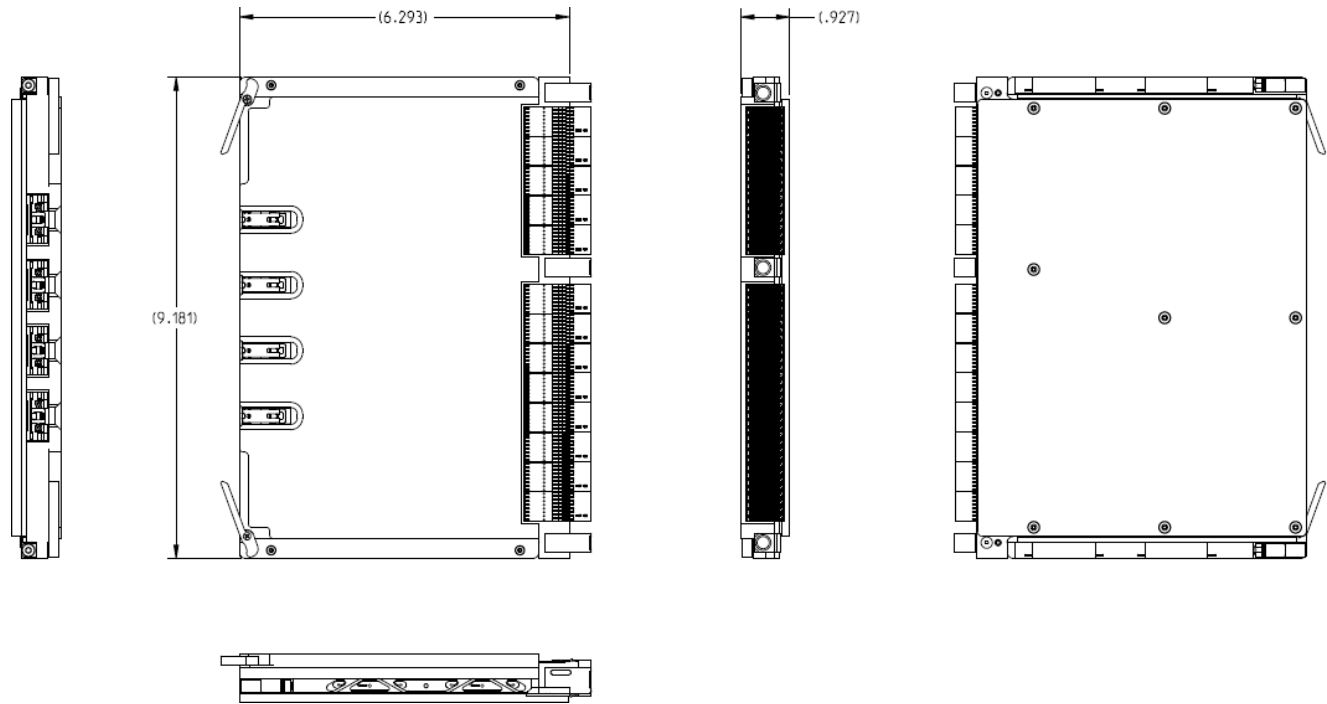
SOFTWARE FEATURES

Stacking
Stacking Ring Topology
Stacking Chain Topology
Stacking Members and Unit ID
Removing and Replacing Stacking Members
Exchanging Stacking Members
Switching the Stacking Master
Configuring System Time
Configuring Daylight Savings Time
Configuring SNTP
Polling for Unicast Time Information
Polling for Anycast Time Information
Broadcast Time Information
Defining SNTP Settings
Configuring Device Security
Configuring Management Security
Configuring Authentication Methods
Defining Access Profiles
Defining Profile Rules
Defining Authentication Profiles
Mapping Authentication Methods
Defining RADIUS Settings
Defining TACACS+ Authentication
Configuring Passwords
Defining Local Users
Defining Line Passwords
Defining Enable Passwords
Configuring Network Security
Network Security Overview
Port-Based Authentication
Advanced Port-Based Authentication
Defining Port Authentication Properties
Defining Port Authentication
Configuring Multiple Hosts
Defining Authentication Hosts
Viewing EAP Statistics
Defining Access Control Lists
Defining IP Based Access Control Lists
Defining MAC Based Access Control Lists
Binding Device Security ACLs
Managing Port Security
Enabling Storm Control
Configuring System Logs
Defining General Log Properties
Viewing Memory Logs
Viewing Flash Logs
Defining System Log Servers
Configuring Interfaces
Configuring Ports
Aggregating Ports
Configuring LACP

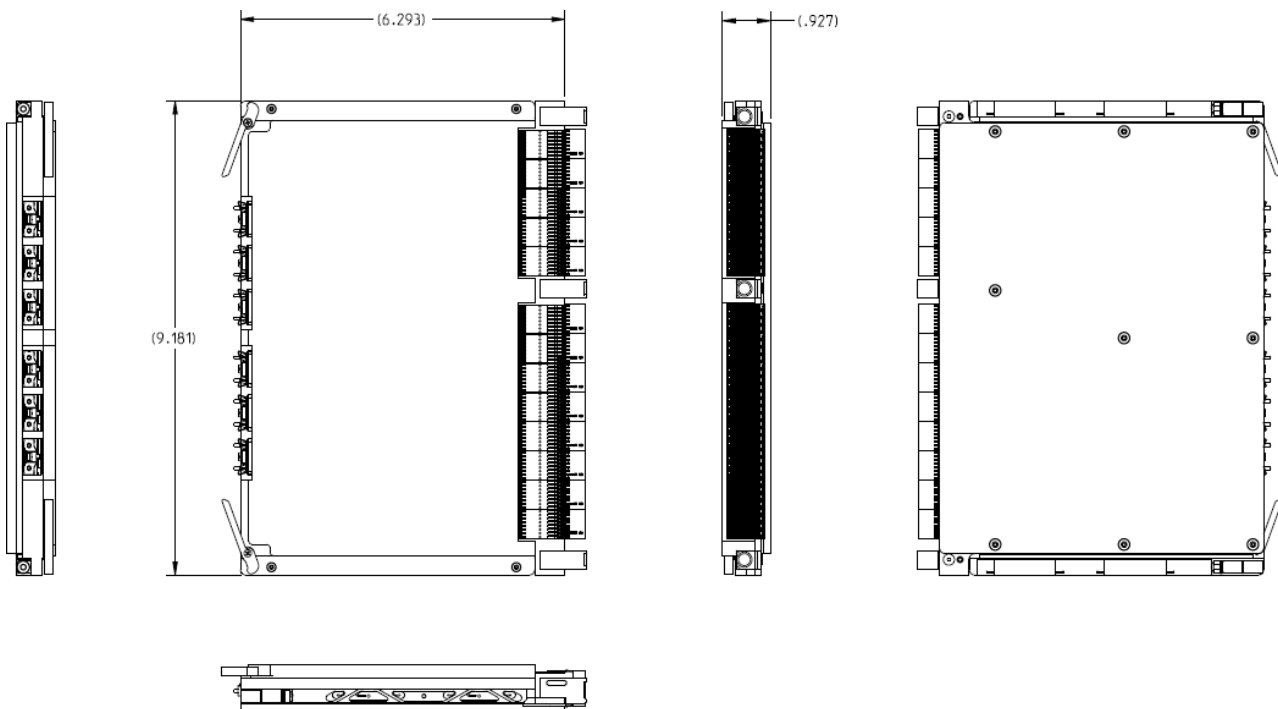
Configuring VLANs
Defining VLAN Properties
Defining VLAN Membership
Defining VLAN Interface Settings
Configuring GARP
Defining GARP
Defining GVRP
Viewing GVRP Statistics
Defining IP Addresses
Configuring IP Addressing
Defining IP Addresses
Defining ARP
Defining Domain Name Servers
Defining DNS Servers
Defining DNS Host Mapping
Defining the Forwarding Database
Defining the Forwarding Database
Defining Access Profiles
Configuring Spanning Tree
Defining Classic Spanning Tree
Defining STP on Interfaces
Defining Rapid Spanning Tree
Defining Multiple Spanning Tree
Defining MSTP Instance Settings
Defining MSTP Interface Settings
Configuring SNMP
SNMP v1 and v2c
SNMP v3
Configuring SNMP Security
Defining SNMP Security
Defining SNMP View
Defining SNMP Group Profiles
Defining SNMP Group Members
Defining SNMP Communities
SNMP Communities Basic Table
SNMP Communities Advanced Table
Configuring SNMP Notifications
Defining SNMP Notification Global Parameters
Defining SNMP Notification Filters
Defining SNMP Notification Recipients
SNMPv1,2c Notification Recipients
SNMPv3 Notification Recipients
Configuring Multicast Forwarding
Multicast Forwarding
Typical Multicast Setup
Multicast Operation
Multicast Registration
Multicast Address Properties
Defining Multicast Properties
Adding MAC Group Address
Adding IP Multicast Groups

Configuring IGMP Snooping
Configuring MLD Snooping
Viewing IGMP/MLD IP Multicast Groups
Defining Multicast Router Ports
Defining Forward All Multicast
Defining Unregistered Multicast Settings
Managing System Files
Downloading System Files
Firmware Download
Configuration Download
Uploading System Files
Upload Type
Software Image Upload
Configuration Upload
Copying Files
Restoring the Default Configuration File
Configuring Quality of Service
Quality of Service Overview
VPT Classification Information
CoS Services
Defining General QoS Settings
Configuring QoS General Settings
Restoring Factory Default QoS Interface Settings
Defining Queues
Defining Bandwidth Settings
Mapping CoS Values to Queues
Mapping DSCP Values to Queues
Defining QoS Basic Mode
Defining Basic Mode Settings
Rewriting Basic Mode DSCP Values
Defining QoS Advanced Mode
Setting Policy Binding
Managing Device Diagnostics
Configuring Port Mirroring
Viewing Statistics
Viewing Interface Statistics
Viewing Interface Statistics
Receive Statistics
Transmit Statistics
Viewing Etherlike Statistics
Managing RMON Statistics
Viewing RMON Statistics
Configuring RMON History
Defining RMON History Control
Viewing the RMON History Table
Configuring RMON Events
Defining RMON Events Control
Viewing the RMON Events Logs
Defining RMON Alarms

CF-02W600-10X



CF-02W600-11X



Frame Components

The primary and secondary frame components are finished in accordance with MIL-DTL-5541 Type II, Class 3 on aluminum alloy. Additional materials and finishes are available upon request.

Extraction Levers

The extraction lever is crafted from 7075-T7351 aluminum alloy and treated with a black anodized finish per MIL-A-8625 Type II, Class 2 specifications.

Wedgelocks

We utilize a variety of wedgelocks per customer requirements, with our standard being the SW5T-475 series from WaveTherm. These wedgelocks are constructed from 6061-T6511 aluminum alloy and black anodized in compliance with MIL-A-8625 Type II, Class 2. They feature 300-series stainless steel fasteners, passivated per AMS2700.

Labeling

Each board is equipped with an identification label, an ESD label, and is protected by a clear overlay.

Board Variants with SOSA VITA91 Connectors

Amphenol has designed these connectors in alignment with The Open Group Sensor Open Systems Architecture™ (SOSA) technical standard, MIL-HD2 provides developers with a readily available, robust open architecture solution for tighter card pitches and chassis designs where space requirements and density are critical. These connectors are available in 3-, 4-, and 6-pair configurations, providing the MIL-embedded market with the highest count of differential pairs available today in a 3U configuration at 56Gb/s PAM 4 speeds. This series was selected by the SOSA Consortium and provides a SOSA aligned solution for nextgen switch and payload card requirements enabling the MIL-embedded market to meet next-gen performance levels while still meeting COTS requirements.

- Highest density with 1.80mm pitch
- 4 diff, 8 column - SOSA aligned configuration
- Data rates scalable to 56Gb/s PAM4 to support system upgrades without costly redesigns
- Proprietary crosstalk reducing technologies
- 15.7mil drill compliant pin allows deeper backdrilling
- Optimized footprints
- Shielded contacts mate before signal contacts, providing up to a 4mm minimum wipe
- Embedded capacitor available
- Differential pairs 28-84 per inch (11-33 differential pairs per centimeter)
- Proven EMI and signal integrity advantages
- Improved impedance matching
- Complete solution for unique customer requirements
- Enables hot plugging
- Meets high density application requirements



Amphenol Ruggedization Pedigree

OVERVIEW:

Amphenol integrated electronic products are designed and manufactured to our Ruggedization guidelines listed below. These guidelines ensure years of reliable operation in harsh environment applications where extreme operating temperatures, shock, vibration, and corrosive atmospheres are regularly experienced. Unless otherwise noted, the parts conform to the below specifications

TEMPERATURE:

- Operating Temperature- Thermal Cycles between -40°C and 85°C while device is operating
- Temperature is measured at chassis housing or card edge
- Storage Temperature- Thermal Cycles between -55°C and 125°C

HUMIDITY:

- Operating Humidity- Humidity cycle between 0-100% non-condensing humidity while device operating
- Storage Humidity- Humidity cycle between 0-100% condensing humidity

SEALING:

- Sealing can be optionally provided at the MIL-DTL-38999 interface with up to 10-5 cc/sec performance

SHOCK AND VIBRATION:

- Sine Vibration - 10g Peak, 5-2,000Hz
 - Based on a sine sweep duration of 10 minutes per axis in each of three mutually perpendicular axes. May be displacement limited from 5 to 44 Hz, depending on specific test.
- Random Vibration - 0.0005 @ 5Hz, 0.1 @ 15 Hz, 0.1 @ 2,000 Hz
 - 60 minutes per axis, in each of three mutually perpendicular axes.
- 40 G Peak Shock Cycle
 - Three hits in each axis, both directions, ½ sine and terminal-peak saw tooth, Total 36 hits.

LUIDS SUSEPTABILITY:

- MIL-DTL-38999 receptacle interface per EIA-364-10E

ALTITUDE:

- -1,500 to 60,000 ft Altitude Testing w/ Rapid Depressurization

ELECTROMAGNETIC COMPATIBILITY:

- Designed to comply with MIL-STD-461E

PRINTED CIRCUIT BOARD ASSEMBLIES:

- Conformal Coat
- Amphenol performs Conformal Coating to both sides of printed circuit board assemblies using HUSMISEAL IB31 in accordance with IPC-610, Class 3.
- Printed Circuit Board Rigidity
- Amphenol printed circuit boards are fabricated in accordance with IPC-6012, Class 3.
- Printed Circuit Board Fabrication
- Amphenol printed circuit boards acceptance criteria is in accordance with IPC-610, Class 3.

RELIABILITY PREDICTIONS (MTBF):

Amphenol can perform Mean Time Between Failure (MTBF) reliability analysis in full compliance with MIL-HDBK-217F-1 Parts Count Prediction and MIL-HDBK-217F-1 Parts Stress Analysis Prediction. We can also perform reliability analyses in full compliance of ANSI/VITA 51.1 if it is required or preferred over the later met.

NOTES:
